

MHF[®] 4 / 4L Connector

MHF 4L Plug Part No. 20565-001R-13

MHF 4 Receptacle Part No. 20449-001E-**

Product Specification

Qualification Test Report No. TR-14142

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7	S22369	August 30, 2022	M. Hidaka	K. Yufu	Y. Hashimoto
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Rev.	ECN	Date	Prepared by	Checked by	Approved by

1. Scope

This Product Specification defines the test conditions and the performances of the MHF 4 / 4L Connector

2. Product Name and Parts No.**2.1 Product Name**

MHF 4 / 4L Connector

2.2 Parts No.

MHF 4L Plug: 20565-001R-13

MHF 4 Receptacle: 20449-001E-**

3. Rating**3.1 Applicable cable****(1) Description**

Inner conductor : AWG#33(7/0.071), Silver plating annealed copper wire

Dielectric core : Fluoro-plastics , diameter 0.63(\pm 0.02)mm , nominal thickness 0.21mm

Outer conductor : 16/6/0.04 , nominal diameter 0.85mm, Copper-Polyester tape + Sn plating annealed copper wire

Jacket : Fluoro-plastics , diameter 0.95(\pm 0.04)mm

(2) Requirements

Characteristic impedance : $50 \pm 5 \Omega$ by TDR method

Nominal capacitance(Reference value): 97 pF/m

Conductor resistance of inner conductor at 293K (20°C)(Reference value) : 752 Ω /km

Insulation resistance : 1,000 M Ω ·km MIN.

Dielectric withstand voltage : no breakdown at AC 500V for 1 minutes.

3.2 Conditions

Voltage: 60 Vr.m.s AC

Operating Temperature: 233~363K(-40°C~+90°C)

(Containing temperature rise by current)

Nominal characteristic impedance: 50 Ω

Frequency: DC~9 GHz

VSWR: [Plug] 1.30 MAX at 0.1~3 GHz

1.45 MAX at 3~6 GHz

1.60 MAX at 6~9 GHz

1.90 MAX at 9~12 GHz

[Receptacle] 1.30 MAX at 0.1~3 GHz

1.40 MAX at 3~6 GHz

1.55 MAX at 6~9 GHz

3.3 Storage Conditions

Storage temperature: 248 to 333K(-25°C to 60°C)

Storage humidity: 85% max. (Non-condensing)

4. Test and Performance**Test Condition**

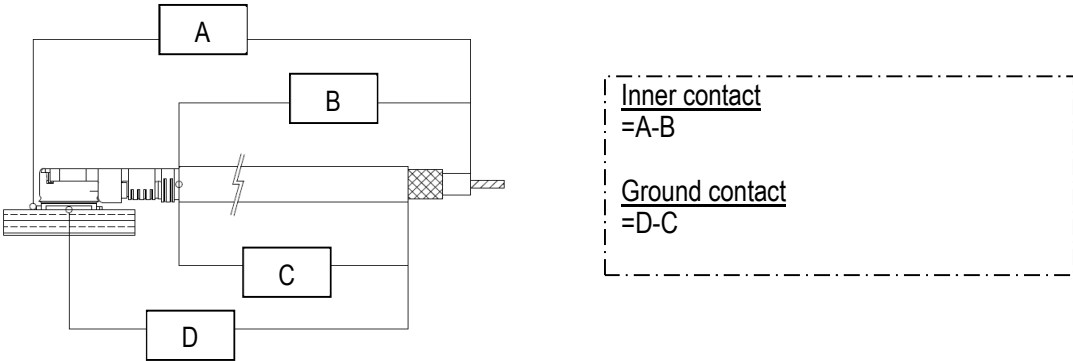
This initial test is equal to it's at shipping condition and unless otherwise specified, all tests and measurements shall be performed under the following conditions in accordance with MIL-STD-202.

Temperature... 288K~308K (15°C~35°C)

Pressure... 866hPa~1066hPa (650mmHg~800mmHg)

Relative humidity... 45~75%R.H.

4.1. Electrical Performance

1. Contact resistance	
Reference standard:	MIL-STD-202-307
Test conditions:	Solder the receptacle connector to the test board and mate the plug connector together, then measure the contact resistance as shown in Fig.1 by the four terminal methods. Apply the low level condition of 20mV MAX. DC for the open circuit voltage and 10mA MAX. DC for the closed circuit current.
	
Fig. 1 Contact resistance	
Pass criteria:	Contact Initial: 20 mΩ MAX. After testing: \triangleleft R20 mΩ MAX. Ground contact Initial: 20 mΩ MAX. After testing: \triangleleft R20 mΩ MAX.

2. Insulation resistance	
Reference standard:	MIL-STD-202-302
Test conditions:	Mate the plug and receptacle connector together, and then apply DC 100 V between the inner contact and the ground contact.
Pass criteria:	Initial: 500 MΩ MIN. After testing: 100 MΩ MIN.

3. Dielectric withstanding voltage	
Reference standard:	MIL-STD-202-301
Test conditions:	Mate the receptacle and plug connector together, then apply AC 200V(rms) between the neighboring contacts for a minute.
Pass criteria:	No creeping discharge, flashover, no insulator breakdown shall occur.

4.1. Electrical Performance

4.VSWR	
Reference standard:	-
Test conditions:	Measure the VSWR as shown in Fig. 2 by the network analyzer. Frequency : 0.1GHz ~ 12GHz
Fig. 2 VSWR	
Pass criteria:	PLUG: 1.30 MAX. at 0.1~3GHz, 1.45 MAX. at 3~6GHz 1.60 MAX. at 6~9GHz, 1.90 MAX. at 9~12GHz RECEPTACLE: 1.30 MAX. at 0.1~3GHz, 1.40 MAX. at 3~6GHz, 1.55MAX. at 6~9GHz

4.2. Mechanical Performance

1. Mating force and Un-mating force	
Reference standard:	-
Test conditions:	Solder the receptacle connector to the test board, then place the board and plug on push-on/pull-off machine, measure of initial and mating/unmating 30 cycles at a speed 25±3mm/min. along the mating axis.
Pass criteria:	Mating force Initial: 30 N MAX. 30cycles: 30 N MAX. Unmating force Initial: 20 N MAX., 5 N MIN. 30cycles: 20 N MAX., 3 N MIN..

2. Crimp strength	
Reference standard:	-
Test conditions:	Pull the cable as shown in Fig-3 at speed of 25±3mm/minutes by the tensile strength machine and measure the retention force.
Fig. 3 Crimp strength	
Pass criteria:	8N MIN.

4.3. Environmental Performance**3. Humidity(Steady state)**

Reference standard: MIL-STD-202-103, Condition A.

Test conditions: Solder the receptacle connector to the test board, then mate plug connector, and expose them to the following environment.
 Temperature: $313\pm 2\text{K}$ ($40\pm 2^\circ\text{C}$)
 Humidity: 90~95%RH
 Duration: 96 hours

Pass criteria: Contact resistance: Shall meet 4.1.1.
 Insulation resistance: Shall meet 4.1.2.
 Dielectric withstanding voltage: Shall meet 4.1.3.
 Appearance: No abnormality adversely affecting the performance shall occur

4. Saltwater spray

Reference standard: MIL-STD-202-101, Condition B

Test conditions: Solder the receptacle connector to the test board, then mate plug connector, and expose them to the following environment.
 Temperature: $308\pm 2\text{K}$ ($35\pm 2^\circ\text{C}$)
 Salt water density: $5\pm 1\%$ [by weight]
 Duration: 48 hours

Pass criteria: Contact resistance: Shall meet 4.1.1.
 Appearance: No abnormality adversely affecting the performance shall occur

5. H₂S gas

Reference standard: -

Test conditions: Solder the receptacle connector to the test board, then mate plug connector, and expose them to the following environment.
 Temperature: $313\pm 2\text{K}$ ($40\pm 2^\circ\text{C}$)
 Relative humidity: $80\pm 5\%$ RH
 Gas: H₂S 3 ± 1 ppm
 Duration: 48 hours

Pass criteria: Contact resistance: Shall meet 4.1.1.
 Appearance: No abnormality adversely affecting the performance shall occur.

4.4.Others

1. Solder ability	
Reference standard:	MIL-STD-202-208
Test conditions:	Dip the solder tine of the contact in the solder bath at $518 \pm 5K$ ($245 \pm 5^{\circ}C$) for 5 ± 0.5 seconds after immersing the tine in the flux of RMA or R type for 5 to 10 seconds.
Pass criteria:	The surface of the dipped contact must become 95% wet and the non-wetted pinholes must not accumulate in one area but be distributed and must be less than 5% of the contact area to be soldered.

2. Soldering heat resistance	
Reference standard:	-
Test conditions:	Reflow temperature profile as shown in Fig. 4. The number of times of reflow is within 2.
<p>The graph shows a reflow temperature profile. The y-axis represents temperature in Kelvin (K) and the x-axis represents time in seconds. The profile consists of several stages: a ramp up to a plateau at 423-473 K (150-200°C) for a duration of 60-120 seconds; a second ramp up to a peak at 533 K; a dwell at the peak for 30 seconds; a ramp down; a secondary peak at 528 K; and a final ramp down. Dashed horizontal lines indicate the temperature levels for 533 K, 528 K, and 423-473 K (150-200°C). Horizontal arrows indicate the durations for the 60-120 second plateau and the 30 second dwell at the 533 K peak.</p>	
Fig. 4 Reflow Temperature Profile	
Pass criteria:	No abnormality adversely affecting the performance shall not occur.

4.5 Test Sequence and Specimen Quantity

Table 1 Test Sequence and Sample Quantity

Test Item	Group														
	A	B	C	D	E	F	G	H	J	K	L	M	N	P	
Contact resistance					1,3	1,3	1,3	1,5	1,3	1,5	1,3	1,3			
Insulation resistance								2,6		2,6					
Dielectric withstanding voltage	1							3,7		3,7					
VSWR		1													
Mating force Unmating force			1												
Crimp strength				1											
Durability					2										
Vibration						2									
Shock							2								
Thermal shock								4							
High temperature life									2						
Humidity (Steady State)										4					
Saltwater spray											2				
H ₂ S gas												2			
Solder ability													1		
Soldering heat resistance														1	
Specimen quantity. (pcs.)	Plug	10	10	10.	10	10	10	10	10	10	10	10	10	-	-
	Receptacle		5		-									10	10

※Numbers indicate sequence in which tests are performed.

5. Recommended Metal Mask

Refer to drawing for the recommended metal mask thickness and opening dimension.